

Title (en)

DEVICE AND METHOD FOR THE LASER-SUPPORTED BENDING OF WORKPIECES

Title (de)

VERFAHREN UND VORRICHTUNG ZUM LASERUNTERSTÜTZTEN BIEGEN VON WERKSTÜCKEN

Title (fr)

PROCÉDÉ ET DISPOSITIF DE PLIAGE DE PIÈCES ASSISTÉ PAR LASER

Publication

**EP 2448690 B1 20141231 (DE)**

Application

**EP 10744651 A 20100628**

Priority

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- AT 10122009 A 20090629

Abstract (en)

[origin: WO2011000012A1] The invention relates to a method for guiding and distributing high-energy radiation (18), in particular laser radiation, in the tool base body (7) of a snaker (3), in particular a V-shaped snaker (13), comprising a bending recess (1) in the tool base body (7) and a radiation exit opening (17) arranged therein for locally heating a workpiece (2) bearing against a contact surface (10) of the snaker (3). According to the invention, high-energy radiation (18) is introduced from a radiation source (20) arranged outside the tool base body (7) into the tool base body (7) through a radiation entry opening (22) and high-energy radiation (18) is discharged to the bending recess (11) through the radiation exit opening (17). At least one concentrated high-energy radiation beam (21) is introduced into the tool base body (7) through at least one radiation entry opening (22) and is at least partially deflected by at least one radiation influencing device (25) in the tool base body (7), expanded and guided through the radiation exit opening (17) onto the workpiece (2).

IPC 8 full level

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